

## 2A, 200V - 1000V Fast Recovery Surface Mount Rectifier

### FEATURES

- AEC-Q101 qualified
- Glass passivated chip junction
- Ideal for automated placement
- Low power loss, high efficiency
- Fast switching for high efficiency
- Low profile package
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free

KEY PARAMETERS		
PARAMETER	VALUE	UNIT
$I_F$	2	A
$V_{RRM}$	200 - 1000	V
$I_{FSM}$	50	A
$T_{JMAX}$	175	°C
Package	SOD-128	
Configuration	Single die	

### APPLICATIONS

- Freewheeling
- Snubber
- DC/DC converters
- Automotive application


**SOD-128**


### MECHANICAL DATA

- Case: SOD-128
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.027g (approximately)

ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)								
PARAMETER	SYMBOL	RS2D FSH	RS2G FSH	RS2J FSH	RS2K FSH	RS2M FSH	UNIT	
Marking code on the device		RS2DFH	RS2GFH	RS2JFH	RS2KFH	RS2MFH		
Repetitive peak reverse voltage	$V_{RRM}$	200	400	600	800	1000	V	
Reverse voltage, total rms value	$V_{R(RMS)}$	140	280	420	560	700	V	
Forward current	$I_F$	2						A
Surge peak forward current, single half sine-wave superimposed on rated load	$t = 8.3\text{ms}$	$I_{FSM}$					50	A
	$t = 1.0\text{ms}$							140
Junction temperature	$T_J$	-55 to +175						°C
Storage temperature	$T_{STG}$	-55 to +175						°C

<b>THERMAL PERFORMANCE</b>			
<b>PARAMETER</b>	<b>SYMBOL</b>	<b>TYP</b>	<b>UNIT</b>
Junction-to-lead thermal resistance	$R_{\theta JL}$	16	°C/W
Junction-to-ambient thermal resistance	$R_{\theta JA}$	73	°C/W
Junction-to-case thermal resistance	$R_{\theta JC}$	14	°C/W

**Thermal Performance Note:** Units mounted on PCB (5mm x 5mm Cu pad test board)

<b>ELECTRICAL SPECIFICATIONS</b> ( $T_A = 25^\circ\text{C}$ unless otherwise noted)						
<b>PARAMETER</b>		<b>CONDITIONS</b>	<b>SYMBOL</b>	<b>TYP</b>	<b>MAX</b>	<b>UNIT</b>
Forward voltage <sup>(1)</sup>	RS2DFSH RS2GFSH RS2JFSH	$I_F = 1\text{A}, T_J = 25^\circ\text{C}$	$V_F$	0.93	-	V
		$I_F = 2\text{A}, T_J = 25^\circ\text{C}$		1.01	1.30	V
		$I_F = 1\text{A}, T_J = 125^\circ\text{C}$		0.78	-	V
		$I_F = 2\text{A}, T_J = 125^\circ\text{C}$		0.88	1.02	V
	RS2KFSH RS2MFSH	$I_F = 1\text{A}, T_J = 25^\circ\text{C}$		0.98	-	V
		$I_F = 2\text{A}, T_J = 25^\circ\text{C}$		1.06	1.30	V
		$I_F = 1\text{A}, T_J = 125^\circ\text{C}$		0.83	-	V
		$I_F = 2\text{A}, T_J = 125^\circ\text{C}$		0.93	1.05	V
Reverse current @ rated $V_R$ <sup>(2)</sup>	$T_J = 25^\circ\text{C}$		$I_R$	-	1	$\mu\text{A}$
	$T_J = 125^\circ\text{C}$			-	40	$\mu\text{A}$
Reverse recovery time	RS2DFSH RS2GFSH	$I_F = 0.5\text{A}, I_R = 1.0\text{A}, I_{rr} = 0.25\text{A}$	$t_{rr}$	-	150	ns
	RS2JFSH			-	250	ns
	RS2KFSH RS2MFSH			-	500	ns
Junction capacitance	RS2DFSH RS2GFSH RS2JFSH	1MHz, $V_R = 4.0\text{V}$	$C_J$	11	-	pF
	RS2KFSH RS2MFSH			10	-	pF

**Notes:**

- (1) Pulse test with  $PW = 0.3\text{ms}$
- (2) Pulse test with  $PW = 30\text{ms}$

<b>ORDERING INFORMATION</b>		
<b>ORDERING CODE<sup>(1)</sup></b>	<b>PACKAGE</b>	<b>PACKING</b>
RS2xFSH	SOD-128	14,000 / Tape & Reel

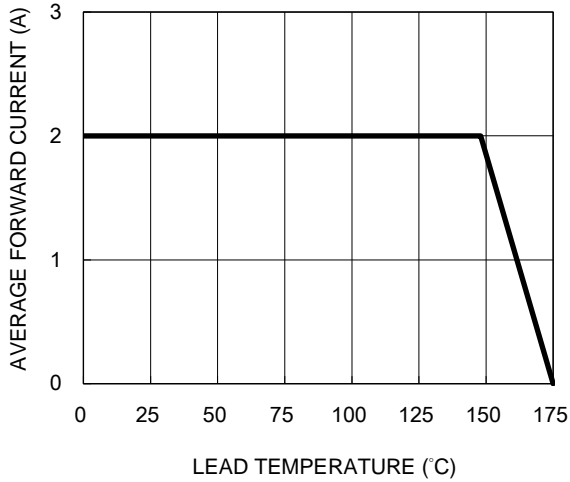
**Notes:**

- (1) "x" defines voltage from 200V(RS2DFSH) to 1000V(RS2MFSH)

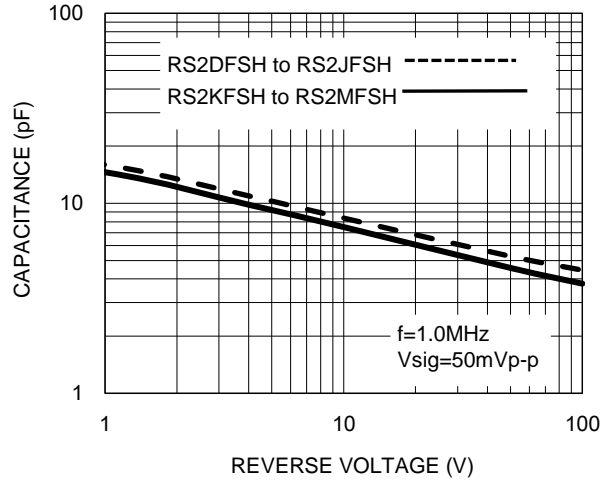
**CHARACTERISTICS CURVES**

( $T_A = 25^\circ\text{C}$  unless otherwise noted)

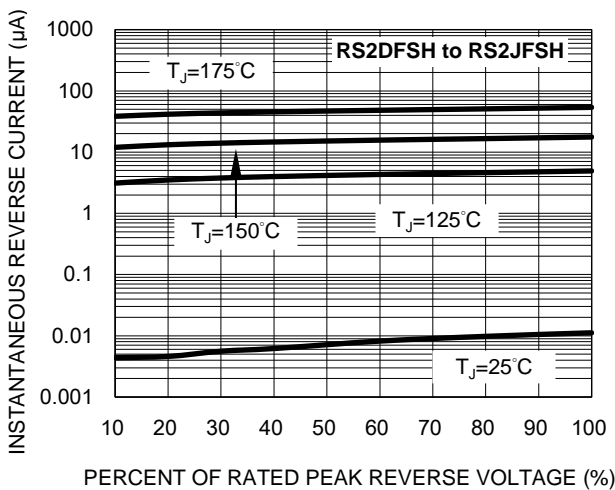
**Fig.1 Forward Current Derating Curve**



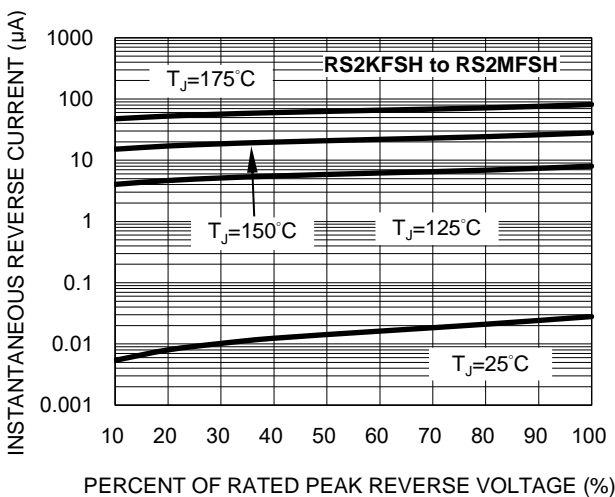
**Fig.2 Typical Junction Capacitance**



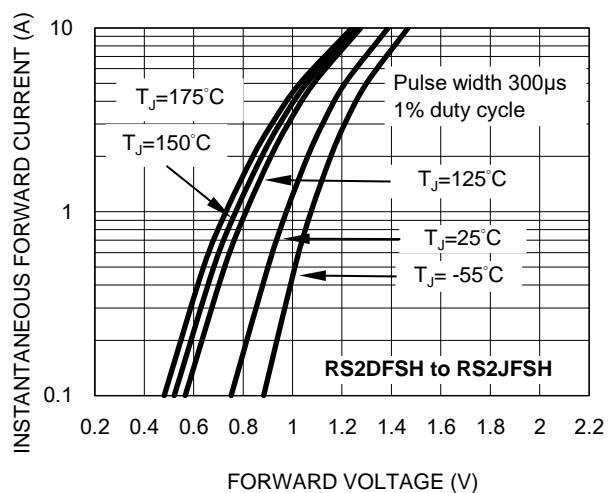
**Fig.3 Typical Reverse Characteristics**



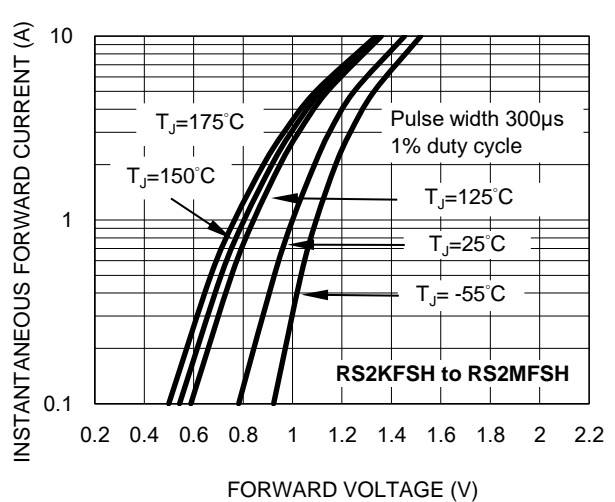
**Fig.5 Typical Reverse Characteristics**



**Fig.4 Typical Forward Characteristics**



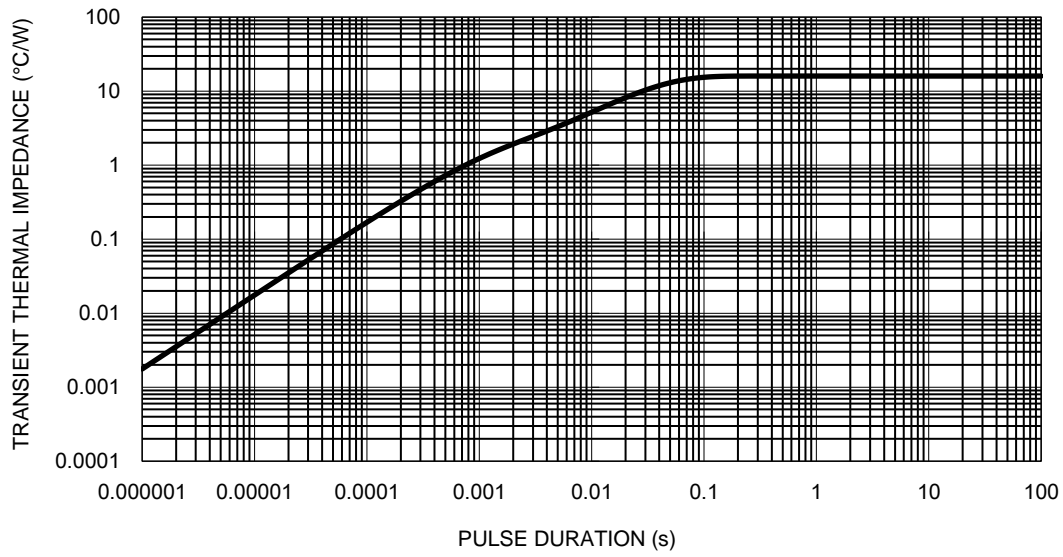
**Fig.6 Typical Forward Characteristics**



**CHARACTERISTICS CURVES**

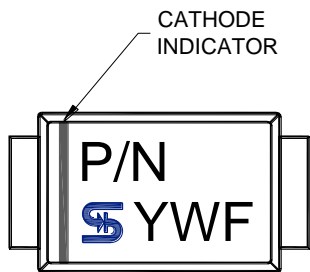
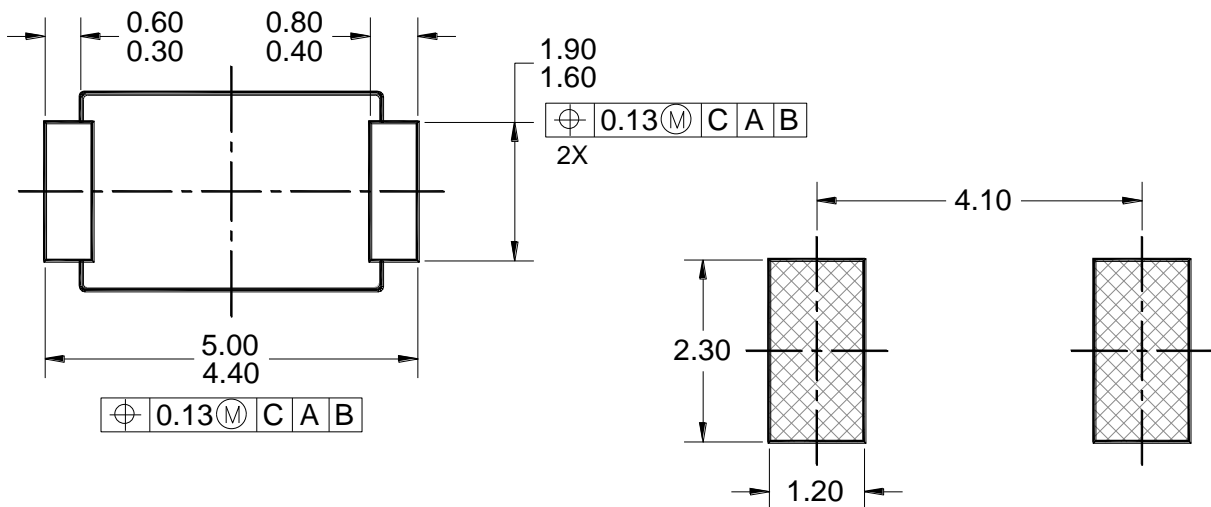
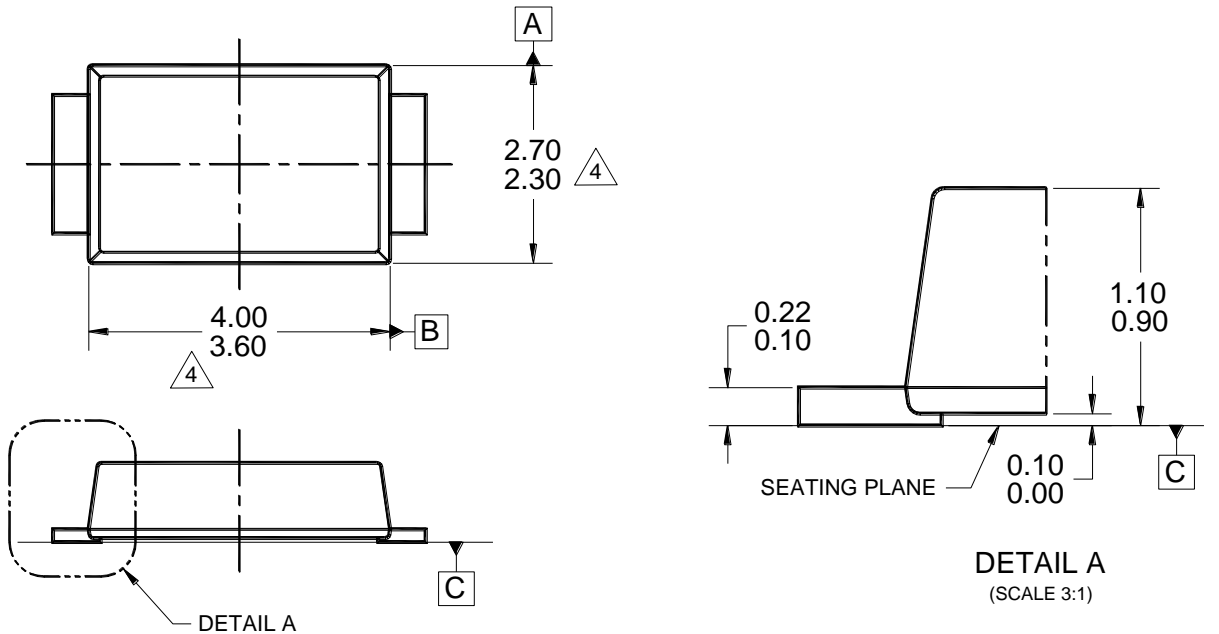
(T<sub>A</sub> = 25°C unless otherwise noted)

**Fig.7 Typical Transient Thermal Impedance**



**PACKAGE OUTLINE DIMENSIONS**

**SOD-128**



**MARKING DIAGRAM**

P/N = MARKING CODE  
YWF = DATE CODE  
F = FACTORY CODE

**NOTES: UNLESS OTHERWISE SPECIFIED**

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.
3. PACKAGE OUTLINE REFERENCE: JEDEC DO-221, VARIATION AD, ISSUE B.
4. MODIFIED PLASTIC BODY DIMENSIONS DO NOT INCLUDE MOLD FLASH.
5. DWG NO. REF: HQ2SD07-SOD128-039 REV A.

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